IN THE CLAIMS

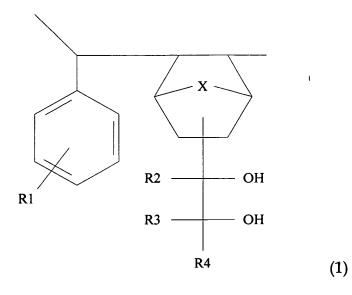
The preamble of claims 1-10 have been amended.

- (Currently Amended) A photoresist photoresistive material comprising:
 <u>a negative tone photoresist having at least a cycloolefin</u>
 functionalized with a di-ol.
- (Currently Amended) The photoresist photoresistive material of claim 1, further comprising:
 an aromatic structure copolymerized with the cycloolefin.
- 3. (Currently Amended) The photoresist photoresistive material of claim 2, further comprising a molecule bonded to the aromatic structure, wherein the molecule is selected from a group consisting of a hydrogen atom, an alkyl group, or a hydroxyl group.
- (Currently Amended) The photoresist photoresistive material of claim 1, wherein the di-ol comprises an alkyl functionalized by two hydroxyl groups.

- 5. (Currently Amended) The photoresist photoresistive material of claim 1, wherein the di-ol further comprises additional functional groups, each functional group being selected from a group consisting of a hydrogen atom, an alkyl group, an aromatic structure, or a cage.
- 6. (Currently Amended) The photoresist photoresistive material of claim 1, wherein the cycloolefin is an aromatic structure.
- 7. (Currently Amended) The photoresist photoresistive material of claim 1, wherein the cycloolefin is a norbornene structure.
- 8. (Currently Amended) The photoresist photoresistive material of claim 7, wherein the norbornene structure comprises a side-group, wherein the side-group is selected from a group consisting of a carbon atom, and alkyl group, an oxygen atom, or a sulfur atom.
- (Currently Amended) The photoresist photoresistive material of claim 2, further comprising a photo acid generator (PAG).

10. (Currently Amended) A <u>negative tone</u> photoresist comprising:

a copolymerized structure represented by the following molecule



where R1 is a hydrogen atom, an alkyl, or a hydroxyl, where each of R2, R3 and R4 is a hydrogen atom, alkyl, aromatic, and/or cage, and where X is no atom, a carbon atom, an alkyl, an oxygen atom, or a sulfur atom.

11. (Currently Amended) A method comprising:

depositing a <u>negative tone</u> photoresist comprising a cycloolefin functionalized with a di-ol on an underlying layer; and

exposing at least a portion of the <u>negative tone</u> photoresist to radiation to form at least a carbonate containing material.

12. (Original) The method of claim 11, wherein the carbonate containing material is a ketone.

- 13. (Original) The method of claim 11, wherein the carbonate containing material is a aldehyde.
- 14. (Original) The method of claim 11, wherein the underlying layer is a substrate.
- 15. (Cancelled) The method of claim 11, wherein the photoresist is a negative tone photoresist.
- 16. (Currently Amended) The method of claim 11, wherein exposing at least a portion of the <u>negative tone</u> photoresist to radiation is done through a mask.
- 17. (Original) The method of claim 11, wherein the radiation is generated from an EUV exposure tool.
- 18. (Currently Amended) The method of claim 11, further comprising baking the <u>negative tone</u> photoresist.
- 19. (Currently Amended) The method of claim 11, wherein the <u>negative tone</u> photoresist further comprises a first aromatic structure copolymerized with the cycloolefin.

- 20. (Original) The method of claim 19, wherein the first aromatic structure is functionalized with a first functional group.
- 21. (Original) The method of claim 20, wherein the first functional group is selected from a group consisting of a hydrogen atom, an alkyl group, or a hydroxyl group.
- 22. (Original) The method of claim 19, wherein the di-ol comprises an alkyl functionalized by two hydroxyl groups.
- 23. (Original) The method of claim 22, wherein the di-ol further comprises a second, a third, and a fourth functional group, wherein each of the second, third, and fourth functional groups is a hydrogen atom, an alkyl group, an aromatic structure, or a cage.
- 24. (Currently Amended) The method of claim 11, wherein depositing the negative tone photoresist on an underlying layer comprises: spin-coating the negative tone photoresist on the underlying layer.

- 25. (Currently Amended) The method of claim 11, further comprising developing the <u>negative tone</u> photoresist layer by depositing a developer solution on the <u>negative tone</u> photoresist layer.
- 26. (Original) The method of claim 25, wherein the developer is TMAH.
- 27. (Original) The method of claim 26, wherein the developer is 2.38% TMAH.
- 28. (Currently Amended) The method of claim 25, further comprising stripping the at least a portion of the <u>negative tone</u> photoresist layer exposed to UV rays.
- 29. (new) The method of claim 11, wherein after exposure, the exposed portion of the negative tone photoresist is less solulable to a developer solution.
- 30. (new) A photoresist comprising:
 - a cycloolefin functionalized with a di-ol, the di-ol, upon exposure to light, to undergo a pinacol rearrangement, wherein after the pinacol rearrangement the photoresist is less solulable in a developer solution.

- 31. (new) The method of claim 30, wherein the photoresist further comprises a first aromatic structure copolymerized with the cycloolefin, the first aromatic structure functionalized with a first functional group.
- 32. (new) The method of claim 31, wherein the first functional group is selected from a group consisting of a hydrogen atom, an alkyl group, or a hydroxyl group.